

SID

Factory: Rot am See

Article:

741

ML6

Provided:

Kracht, Enrico

Customer:

Date:

02.09.2016



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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Polyimid 50µ -18µ eins CU Kleberlos 460x305...	50201120	<div>18</div> <div>50</div>	VS	<div>1</div> <div></div>	
A-RS-FR4-Prepreg-106-LowFlow-R1551LE	50200912	<div>50</div>		<div>2</div> <div></div>	A01
A-RS-FR4-ML-0.25mm-018+018-TG150-HF	50200928	<div>18</div> <div>250</div> <div>18</div>	L2 L3	<div>3</div> <div></div>	A02
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	<div>110</div>		<div>4</div> <div></div>	B00
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	<div>0</div>		<div>5</div> <div></div>	
A-RS-FR4-ML-0.25mm-018+018-TG150-HF	50200928	<div>18</div> <div>250</div> <div>18</div>	L4 L5	<div>6</div> <div></div>	A03
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	<div>57</div>		<div>7</div> <div></div>	
A-RS Kupferfolie-018my 330x490mm	50200238	<div>18</div>	RS	<div>8</div> <div></div>	

Thickness after Pressing

B00:

890 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

990 µm

Dmin:

790 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1000 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

1100 µm

Dmin:

900 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

875 µm

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